

## C1812X222KBRACTU

**Specifications** 

Insulation Resistance

Aliases (C1812X222KBRAC7800) SMD Comm X7R HV Flex, Ceramic, 2,200 pF, 10%, 630 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	95 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1.4mm +/-0.15mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Capacitance	2,200 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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